

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	H01121/306
Suggested Group Art Unit::	
CD-ROM or CD-R?::	None
Number of CD disks::	
Number of Copies of CDs::	
Sequence Submission?::	None
Computer Readable Form (CRF)::	No
Number of copies of CRF::	0
Title::	SEMICONDUCTOR DEVICE MANUFACTURING METHOD FOR IMPROVING ADHESIVITY OF COPPER METAL LAYER TO BARRIER LAYER
Attorney Docket Number::	8017-1120
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	2C
Total Drawing Sheets::	3
Small Entity?::	No
Latin Name::	
Variety Denomination Name::	
Petition Included?::	No
Petition Type::	
Licensed US Gov't Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: JAPANESE
Status:: Full Capacity
Given Name:: NORIO
Middle Name::
Family Name:: OKADA
City of Residence:: KANAGAWA
State or Province of
Residence::
Country of Residence:: JAPAN
Street of Mailing 1753 SHIMONUMABE
Address:: NAKAHARA-KU, KAWASAKI
City of Mailing Address:: KANAGAWA
State or Province of Mailing Address::
Country of Mailing Address:: JAPAN
Postal or Zip Code of Mailing Address::

Correspondence Information

Correspondence Customer 000466
Number::

Representative Information

Representative Customer	000466
Number::	

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::

Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
JAPAN	2003-021956	1/30/03	Yes

Assignment Information

Assignee Name:: NEC ELECTRONICS CORPORATION

Street of Mailing 1753 SHIMONUMABE

Address:: NAKAHARA-KU, KAWASAKI

City of Mailing Address:: KANAGAWA

State or Province of Mailing Address::

Country of Mailing Address:: JAPAN

Postal or Zip Code of Mailing Address:: 211-8668